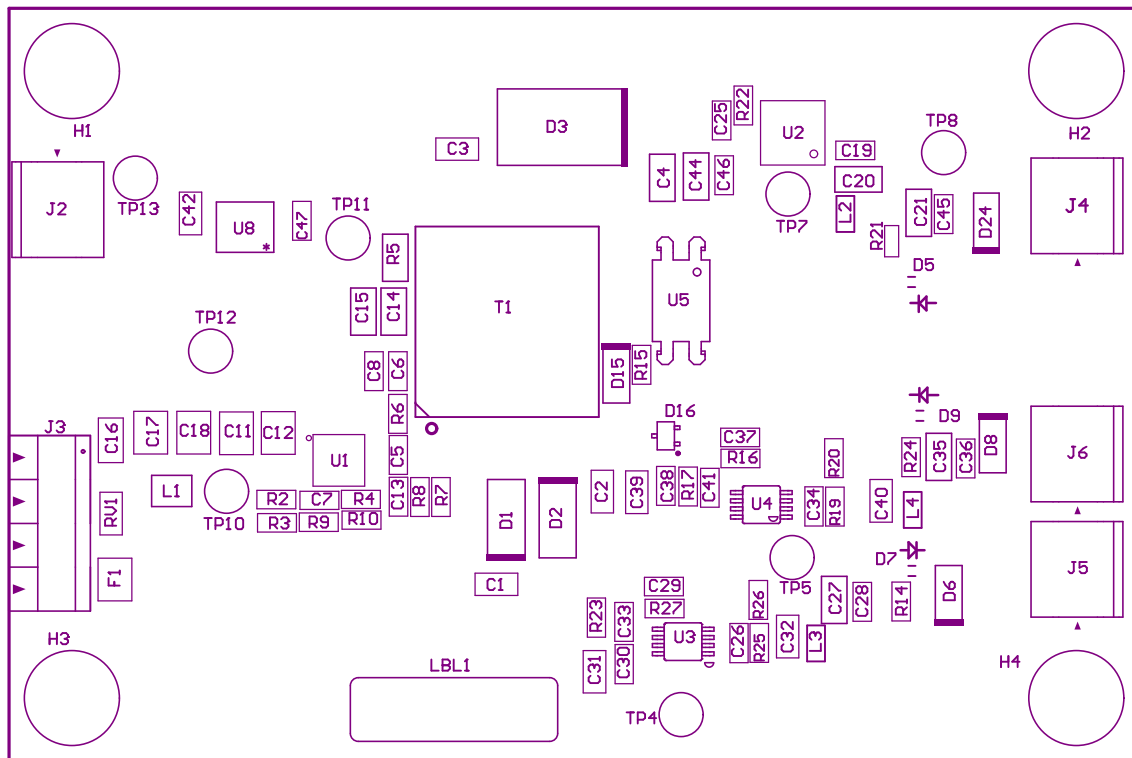


- ZZ1 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ3 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ4 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #:	TIDA-00401	REV: E1	SUN REV:	Not In VersionControl
IGNORE ->	ASSEMBLY TOP				
PLOT NAME =	Top Assembly Drawing	GENERATED :	6/23/2015	11:14:59 AM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00401	REV: E1	SUN REV: Not In VersionControl
	IGNORE ->		ASSEMBLY BOTTOM
PLOT NAME = Bottom Assembly Drawing	GENERATED :	6/23/2015 11:14:59 AM	TEXAS INSTRUMENTS

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